

iMAPS New England 43 Symposium & Expo Exhibitors

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100 Flagship Drive
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www.advancerepro.com
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E: d.robinson@advancerepro.com
T: 978-685-2911
Description: photomasks

ATV Technologie GmbH
Booth 211
Johann-Sebastian-Bach-Str. 38
Vaterstetten, Germany 85591
www.atv-tech.de
Contact: Siegfried Kowalsky
E: sales@atv-tech.de
T: 08106-3050-0
Description: Vacuum reflow, Quartz tube furnace

CREYR INNOVATION
Booth 410
P.O. BOX 1558
East Greenwich, Rhode Island 02818
www.creyr.net
Contact: Jim McLenaghan
E: ajm@creyr.net T: 401-885-5444
Description: New England Technology Solutions Providers & Manufacturer's Representatives for: Akrometrix, PCB Substrate & Component Warpage Inspection Systems; DfR Solutions, Sherlock Automated Design Analysis; Indium Corporation, Solder Materials for Microelectronics Assembly, Brazing, Thermal Interface; Ersu, Rework & Inspection Systems; MicroScreen, Precision Screens & MicroWeld Stencil Technology; Saki Future in Focus, 3D Automated Optical Inspection; Panasonic, Board Level Assembly & Microelectronics Manufacturing Equipment.

Epoxy Technology, Inc.
Booth 613
14 Fortune Drive
Billerica, Massachusetts 01821
www.epotek.com
Contact: Joe McCabe
E: jmccabe@epotek.com T: 978-687-3805
Description: Adhesives Epoxy Technology Inc, a leading manufacturer of high performance specialty epoxy, UV & Hybrid adhesives is celebrating 50 years of adhesive innovation and excellence. EPO-TEK® adhesives are routinely specified by engineers world-wide in a multitude of industries including microelectronics.

AI TECHNOLOGY, INC.
Booth 206
70 Washington Road
Princeton Jct, New Jersey 08550
www.aitechnology.com
Contact: Maurice LeBlon
E: mleblon@aitechnology.com
T: 609-799-9388
Description: manufacture adhesives & TIM AI Technology, Inc. (AIT) specializes in electronic interconnection and microelectronic packaging materials, including adhesive films with low to zero interface stress and Thermal Interface pads, greases, gels, waxes and phase change materials. Other AIT products include Conformal Coatings to combat UV, moisture and humidity corrosion.

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Booth 403
577 Main Street Suite 270
Hudson, Massachusetts 01749
www.centerlinetech-usa.com
Contact: Hugh Muffoletto
E: hugh@centerlinetech-usa.com
T: 978-568-1330
Description: precision lapping and polishing

CWI TECHNICAL SALES
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704 Ginesi Drive
Suite 11A
Morganville, New Jersey 07751
www.cwitechsales.com
Contact: Jonathan Gold
E: tptwirebonder@cwitechsales.com
T: 732-536-3964
Description: Manual & Semi-Automated Wire Bonders

Ferro Ceramic Grinding, Inc.
Booth 116
5 Cornell Place
Wilmington, Massachusetts 01887
www.ferroceramic.com
Contact: Mark Belanger
E: markb@ferroceramic.com
T: 781-245-1833
Description: Ceramic Machining

American Ceramic Society - New England
Booth 617
185 Chestnut St.
Wrentham, Massachusetts 02093
<http://neacers.org>
Contact: John Redman
E: johnfredman@comcast.net
T: 802-999-8360
Description: ACerS Membership

Cirexx International
Booth 213
791 Nuttman St
Santa Clara, California 95054
www.cirexx.com
Contact: Al Wasserzug
E: Morgan@cirexx.com
T: 800-217-0202
Description: PCB fab, assembly, design Cirexx is a Printed Wiring Board manufacturer operating in the heart of Silicon Valley since 1984. The company offers design, fabrication and assembly services of Printed Circuit Boards, including RF/Microwave and HDI boards, and Flexible Printed Circuits, including Rigid-Flex Circuit Boards.

EMA Sales & Marketing, Inc.
Booth 404
19 Red Coat Lane
Plainville, Massachusetts 02762
www.emasalesmarketing.com
Contact: Harvey Smith
E: Harvey@emasalesmarketing.com
T: 508-826-6033
Description: Die Attach Equipment & Materials, Bond testers, AlN & SiN Substrates. We will be demonstrating the Dage 4000PLUS fully Automatic Bond Tester on-site.

Ferro Corporation
Booth 414
6060 Parkland Boulevard
Mayfield Heights, New York 44124
www.ferro.com
Contact: Becci Whitford
E: becci.whitford@ferro.com
T: 315-227-5253
Description: Electronic Materials

**Finetech
Booth 401**

560 E Germann Rd #103
Gilbert, Arizona 85297
www.finetechusa.com
Contact: Neil O'Brien
E: aa@finetechusa.com
T: 480-893-1630

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www.goodarksemi.com
Contact: Gary Pendola
E: gpendola@goodarksemi.com
T: 631-513-1432

Description: Discrete semiconductors; Good-Ark Semiconductor is a leading global discrete semiconductor manufacturer that offers a wide variety of surface mount, through-hole and wafer devices with superior quality and reliability at competitive costs. Good-Ark manufactures innovative discrete semiconductors with increased power density and energy efficiency in pursuit of environmental sustainability and cost effectiveness

**Hesse Mechatronics, Inc.
Booth 212**

225 Hammond Ave.
Fremont, California 94539
www.hesse-mechatronics.com
Contact: Mike McKeown
E: jolynn.snell@hesse-mechatronics.us
T: 480-361-5029

Description: Wire Bond Equipment Hesse GmbH, founded in 1986 and based in Paderborn, Germany, develops and manufactures fully automatic ultrasonic and thermosonic wire bonders and ultrasonic flip chip bonders together with standard or customer-specific automation solutions for the backend semiconductor industry.

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www.dicingusa.com
Contact: Timothy Gonsalves
E: tim@dicingusa.com T: 978-446-0003

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399 Kilvert St
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www.geibrefining.com
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Description: precious metal refining

**GOWANDA ELECTRONICS
Booth 214**

One Magnetics Parkway
Gowanda, New York 14070
www.gowanda.com
Contact: Don Minnick
E: dminnick@gowanda.com
T: 716-532-2234
Description: Magnetics

**i3 Electronics
Booth 503**

1701 North St
Endicott, New York 13760
www.i3electronics.com
Contact: Neal Driver
E: neal.driver@i3electronics.com
T: 866-820-4820
Description: PCB, Semi-conductor Packages and Assembly

**JEOL USA, INC
Booth 607**

11 DEARBORN ROAD
Peabody, Massachusetts 01960
WWW.JEOLUSA.COM
Contact: Robb Westby
E: rwestby@jeol.com T: 978-535-5900
Description: Sample Prep Tools, SEM, TEM, SPOT BEAM JEOL high throughput scanning and transmission electron microscopes allow detailed examination of materials and assemblies for defects, providing high resolution images and elemental data. JEOL direct analysis mass spectrometers rapidly identify chemical compositions of packaging and components. JEOL has more than 60 years of expertise in imaging and analysis.

**Golden Altos
Booth 402**

402 South Hillview Dr
Milpitas, California 95035
www.goldenaltos.com
Contact: Messay Yoftahie
E: messay@goldenaltos.com
T: 408-956-1010
Description: Integrated circuit assembly

**Heraeus Electronics
Booth 605**

24 Union Hill Road
Conshohocken, Pennsylvania 19428
www.heraeus-electronics.com
Contact: Mary Ann Landis
E: maryann.landis@heraeus.com
T: 215-287-9706
Description: Electronic materials

**iMAPS New England
Booth 615**

c/o Jeremy Lug, Metrigraphics
50 Concord Street
Wilmington, Massachusetts 01887
www.imapsne.org
Contact: Jeremy Lug
E: membership@imapsne.org
T: 978-658-6100 X3504
Description: iMAPS Membership

**Kemlab / Transene
Booth 601**

254 West Cummings Pk
Woburn, Massachusetts 01801
www.kemlab.com
Contact: Jeremy Golden
E: Jgolden@kemlab.com T: 781-281-0174
Description: Photoresist, Etchants

**Kyocera America, Inc
Booth 505**

8611 Balboa Ave
San Diego, California 92123
americas.kyocera.com/kai-semiparts
Contact: Ken McQuillan
E: kenneth.mcquillan@kyocera.com
T: 858-614-2592
Description: Semiconductor packaging and assembly

METALLIX REFINING

Booth 113

59 Avenue at the Commons
Suite 201
Shrewsbury, New Jersey 07702
www.metallix.com
Contact: Kelly Warren
E: kellyw@metallix.com T: 800-327-7938
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Booth 112

238 Littleton Road Suite 207
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www.mmstechnicalsales.com
Contact: Peter King
E: info@mmstechnicalsales.com
T: 978-392-0110
Description: Packaging, Boards & Substrates
MMS Technical Sales is a manufacturers' representative providing packaging solutions throughout New England. We offer solutions in the areas of: ceramic substrates and hermetic packages, lids, preforms, getters, thermal management products, laser sealing systems and services, interconnects, as well as traditional printed wiring board technologies.

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Dunbarton, New Hampshire 03046
www.msdsales.com
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E: matt@msdsales.com T: 603-731-5631
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E: maizpurua@laserservicesusa.com
T: 978-692-6180
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MICRO SYSTEMS TECHNOLOGIES

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1839 S. Alma School Road Suite 270
Mesa, Arizona 85210
www.mst.com
Contact: Susan Bagen
E: susan.bagen@mst.com
T: +41 44 804 6300
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Mini-Systems Inc.

Booth 501

20 David Rd
North Attleboro, Massachusetts 02760
www.mini-systemsinc.com
Contact: Craig Tourgee
E: ctourgee@mini-systemsinc.com
T: 508-695-0203
Description: Mini-Systems, Inc. (MSI) is a world class leader in the manufacture of precision passive components and high-reliability hermetic packages. Our products include thick and thin film chip resistors, capacitors, resistor networks, metalized substrates, and glass-to-metal seal packages. MSI products have served the Aerospace, Communication, Military, Medical and Industrial fields reliably for over forty-five years.

Netzsch Instruments North America

Booth 406

129 Middlesex Turnpike
Burlington, Massachusetts 01803
www.netzsch-thermal-analysis.com
Contact: Dave Shepard
E: dave.shepard@netzsch.com
T: 781-418-1801
Description: Thermal Analysis Instruments

LFG Micro

Booth 203

PO Box A
Mastic Beach, New York 11951
www.lfgmicro.com
Contact: Leo Garvey
E: imapsne@lfgmicro.com
T: 631-399-3199
Description: Microelectronic assembly solutions

MicroChem Corp

Booth 413

200 Flanders Rd
Westborough, Massachusetts 01581
www.microchem.com
Contact: Rob Hardman
E: rhardman@microchem.com
T: 617-965-5511
Description: Photoresists and ancillaries

MRSI Systems

Booth 507

101 Billerica Ave. Bldg #3
N. Billerica, Massachusetts 01862
www.mrsisystems.com
Contact: Jon Medernach
E: jon.medernach@mrsisystems.com
T: 978-667-9449
Description: MRSI Systems is a leading supplier of high precision dispense and assembly equipment for the semiconductor and microelectronics industry offering systems for the manufacture of Microwave, Optical, MCM's and MEM's devices. With three decades of advanced packaging application experience, MRSI Systems products support epoxy die bonding, eutectic attach, thermo-compression and flip chip.

NTK Technologies

Booth 215

3979 Freedom Circle Drive Suite 320
Santa Clara, Colorado 94022
www.ntktech.com
Contact: Gil Aguiar
E: cfranks@ntktech.com T: 408-562-5124
Description: Ceramic IC Packaging

P/M INDUSTRIES INC.**Booth 216**

14305 SW Millikan Way
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www.pmindustriesinc.com

Contact: Stephen Knight
E: sk@pmindustriesinc.com

T: 503-601-3205

Description: LASER MACHINING / LAPPING / POLISHING P/M Industries has been a leader in providing contract manufacturing services including CO2 Laser Machining, Laser Resistor Trimming, Diamond Sawing, Precision Lapping and Polishing of Aluminum Nitride, BeO, Alumina and other materials since 1972. We are ISO 9001:2008 registered. Our dedicated staff is here to help you with all your needs and to get the job done right...the first time.

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Contact: Bob Wons
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T: 603-471-9320

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Contact: Bill Lawrence
E: Bill@icproto.com T: 802-309-0327

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Semiconductor Equipment Corp**Booth 611**

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Simi Valley, California 93021
www.semicorp.com

Contact: Don Moore
E: dmoore@semicorp.com

T: 805-529-2293

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PALOMAR TECHNOLOGIES**Booth 415**

2728 Loker Ave. West
Carlsbad, California 92010
www.palomartechnologies.com

Contact: Dale Perry
E: dperry@bonders.com T: 760-931-3681

Description: Wire and Die Bonders; Palomar Technologies, a former Hughes Aircraft subsidiary, is the global leader of automated high-accuracy, large work area die attach and ball/ wedge wire bonding equipment and precision contract assembly services. Customers utilize our products, services and solutions to meet the needs of optoelectronic packaging, complex hybrid assembly and micron-level components.

Protavic America Mereco Technologies**Booth 111**

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Londonderry, New Hampshire 03053
www.protavicamerica.com
www.mereco.com

Contact: Randy Makee
E: rmakee@protavicamerica.com

T: 603-289-2828

Description: Conductive, non conductive adhesives, inks and potting compounds. Die attach, underfills, flexible low temp cure packaging solutions.

Remtec, Inc.**Booth 205**

100 Morse Street
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www.remtec.com

Contact: Lynn Magliozzi
E: lmagliozzi@remtec.com

T: 781-762-9191

Description: Custom Ceramic Substrates and Packages

Sonoscan, Inc.**Booth 102**

2149 E. Pratt Boulevard
Elk Grove Village, Illinois 60007
www.sonoscan.com

Contact: Jack Richtsmeier
E: jrichtsmeier@sonoscan.com

T: 847-437-6400

Description: Acoustic microscopes

Photofabrication Engineering Inc. (PEI)**Booth 511**

500 Fortune Blvd
Milford, Massachusetts 01757
www.photofabrication.com

Contact: Robert Ashman
E: rashman@photofabrication.com

T: 508-478-2025

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Proton OnSite**Booth 109**

10 Technology Dr.
Wallington, Connecticut 06492
www.protononsite.com

Contact: Dave Wolff
E: dwolff@protononsite.com

T: 203-949-8697

Description: Hydrogen generators, Nitrogen generators; Proton OnSite is the global leader in on-site hydrogen generation and innovative gas solutions. Leveraging 20+ years of advanced PEM technology experience to support diverse industrial applications worldwide, we offer hydrogen generation systems ranging in scale from 200 cc/min to 7000 L/min – expandable through modular design for almost unlimited capacity.

Riv Inc.**Booth 201**

31 Railroad Ave
Merrimack, New Hampshire 03054
www.rivinc.com

Contact: Tania Keefe
E: tania@rivinc.com T: 603-424-0510

Description: Thick film screens

Stellar Industries Corp.**Booth 411**

50 Howe Avenue
Millbury, Massachusetts 01527
www.stellarind.com

Contact: Ronald Visser
E: adrift@stellarind.com T: 508-865-1668

Description: Ceramic Substrates

**Tanaka Precious Metals
Booth 103**

235 Vineyard Court
Suite 150
Morgan Hill, California 95037
www.tanaka.co.jp/english
Contact: William Bud Crockett Jr.
E: y-shimada@ml.tanaka.co.jp
T: 408-779-0461
Description: Precious metal materials TANAKA is a Japan-based manufacturer of high purity precious metal products to automotive and semiconductor industries with engineering support in the U.S. TANAKA is ISO/IEC 17025 certified for the analytical techniques of Platinum, Gold, Silver and Palladium, and ISO9001 certified for quality management. We provide Bonding Wire samples including PCC and Al.

**UTZ Technologies
Booth 416**

4 Peckman Rd
Little Falls, New Jersey 07424
www.utz.com
Contact: Jonah Bilotta
E: Jonah@utz.com T: 973-339-1100
Description: Screens and Stencils for Printing
UTZ Technologies is a manufacturer of high quality screens and stencils for printing. Established in 1968 UTZ brings a wealth of knowledge and expertise to both screen and stencil printing technologies, and uses all state of the art manufacturing equipment from automated stretching systems to the very best in laser technology.

**YINCAE Advanced Materials
Booth 101**

19 Walker Way
Albany, New York 12205
www.yincae.com
Contact: Dr. Wusheng Yin
E: wyin@yincae.com T: 518-452-2880
Description: SMT Advanced Materials YINCAE is a global leader and award winner in innovative technology for high performance coatings, adhesives and electronic materials. YINCAE products are designed to facilitate smarter and faster production for customers at lower costs without sacrificing quality.

**TAS Consulting
Booth 104**

7 Windham Circle
Mendon, New York 14506
www.thermalanalysisissystems.com
Contact: Patty McMicken
E: tbarcley@earthlink.net
T: 585-301-7779
Description: Engineering services TAS Consulting is an SMWOB Engineering Services business that contracts to perform:
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**Viatec Instruments
Booth 509**

3 Norway Rd
Milton, Massachusetts 02186
www.viatecinstruments.com
Contact: Bill Hanna
E: bhanna@viatecsales.com
T: 617-717-4906
Description: Inspection, analysis & test equipment ViaTec Instruments represents a range of products that aid in manufacture, inspection, test, probe, and failure analysis of electronic devices, including 625 pin automated curve tracers, bonding/micro-joining & seam-sealing equipment, precision manual & automated dispensing systems, mechanical and chemical decapsulators, laser trim & repair systems. contactor & probe card cleaners.

**Ubotic
Booth 412**

Unit 8, 15F, International Trade Ctr
11 Shatsui Rd
Tsuen Wan, New Territories
www.ubotic.com
Contact: Julie Adams
E: julie.adams@ubotic.com
T: 480-208-1999
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<http://www.xyztec.com>
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Description: Bond Testers



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